

Description

The FS1012 MEMS mass flow sensor module measures the flow rate using the thermo-transfer (calorimetric) principle. The FS1012 is capable of measuring a gas or liquid medium.

The FS1012 offers key advantages over resistor-based flow solutions. The sensor utilizes thermopile sensing, which provides an excellent signal-to-noise ratio. The sensor comprises a “solid” thermal isolation technology and silicon-carbide coating to protect it from abrasive wear and provides robustness and long-term reliability. In comparison, other sensors typically contain a fragile membrane above an etched cavity for the thermal isolation base.

The FS1012 features the sensor fully assembled and wire-bonded out to a 6-pin header.

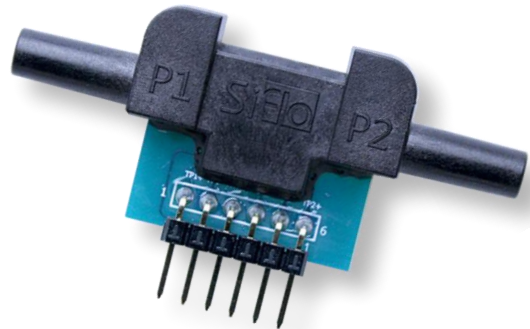
Features

- Gas or liquid mediums
- Robust “solid” isolation technology
- Resistant to surface contamination
- No cavity to cause clogging
- Resistant to vibration and pressure shock
- Low power application
- Sensitive at low flow rates and differential pressure levels
- Fast response: 2ms
- Millivolt output
- Supply voltage: 3V to 5V
- Module operating temperature range: 0°C to +85°C

Typical Applications

- Process controls and monitoring
- Oil and gas leak detection
- HVAC and air control systems
- CPAP and respiratory devices
- Automotive mas air flow meter
- Liquid dispensing system

FS1012 Flow Sensor Module



Basic Application Circuits

Figure 1. Single-Ended Circuit Example

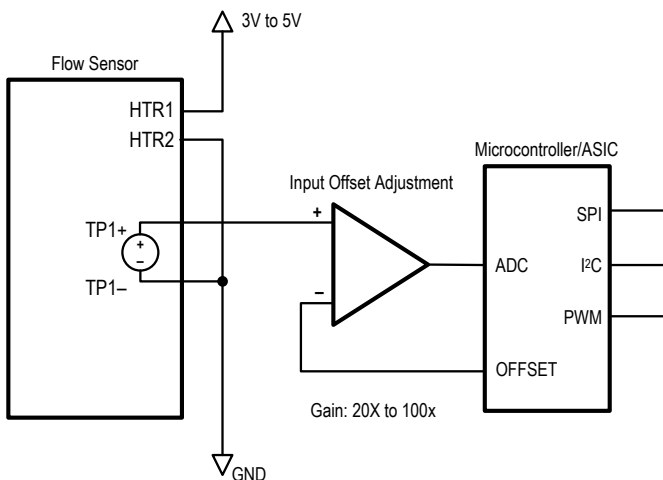
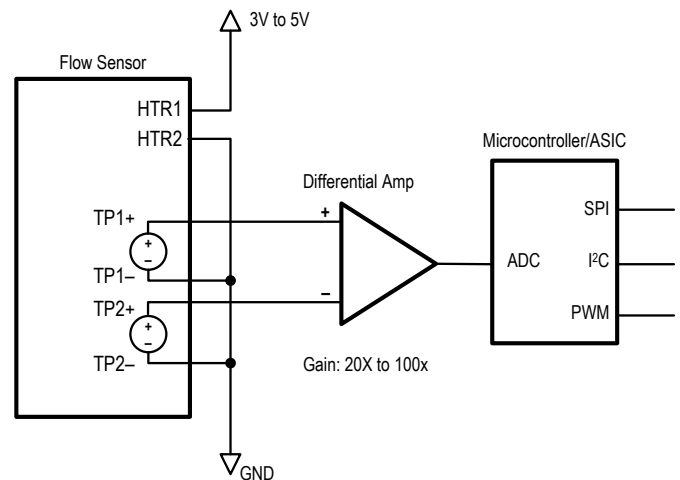
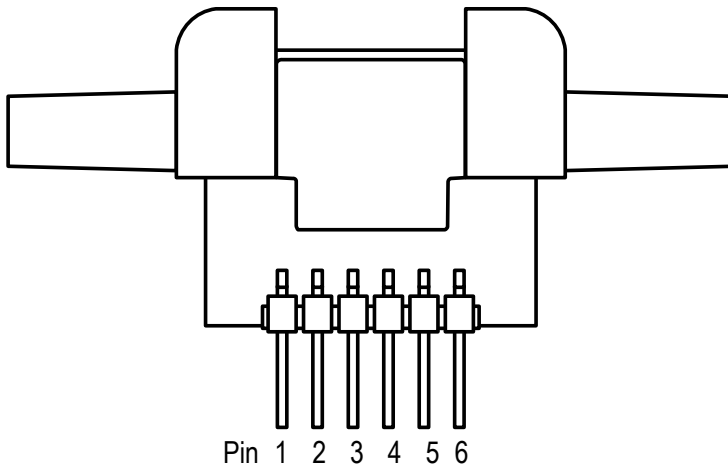


Figure 2. Differential Circuit Example



Pin Assignments

Figure 3. Pin Assignments for Module – Top View



Pin Descriptions

Table 1. Pin Descriptions

Pin Number	Pad Name	Type	Description
1	TP1+	Output	Thermopile 1 (+)
2	TP1-	Output	Thermopile 1 (-)
3	HTR1	Input	Heater
4	HTR2	Input	Heater
5	TP2-	Output	Thermopile 2 (-)
6	TP2+	Output	Thermopile 2 (+)

Absolute Maximum Ratings

The absolute maximum ratings are stress ratings only. Stresses greater than those listed below can cause permanent damage to the device. Functional operation of the FS1012 at absolute maximum ratings is not implied. Exposure to absolute maximum rating conditions may affect device reliability.

Table 2. Absolute Maximum Ratings

Symbol	Parameter	Conditions	Minimum	Maximum	Units
V _H	Heater Voltage Supply			5.6	V
T _{STOR}	Storage Temperature		-50	130	°C

Operating Conditions

Table 3. Recommended Operating Conditions

Symbol	Parameter	Minimum	Typical	Maximum	Units
T _{AMB}	Ambient Operating Temperature ^[a]	0		85	°C
I _{HTR_CC}	Heater Driving Current – Constant Current ^[a]		10	20	mA
V _{HTR_CV}	Heater Driving Voltage – Constant Voltage ^[a]		3	5.6	V

[a] Sensor specifications are tested at the wafer die level.

Electrical Characteristics

Table 4. Electrical Characteristics

Note: See important notes at the end of the table.

Symbol	Parameter	Conditions	Minimum	Typical	Maximum	Units
R _H	Heater Resistor ^[a]		230	290	400	Ω
∞ _{HTR}	Heater Temperature Coefficient of Resistance ^[a]			300		ppm/°C
V _{TP_OUT}	Thermopile Output ^[a]	3V driving voltage, in air, 20°C, no flow	30	35	60	mV
R _{TP}	Thermopile Resistance ^[a]	20°C	100	210	300	KΩ
V _{TP_OUTDIFF}	Thermopile Differential Output ^[a]	3V driving voltage, in air, 20°C, no flow	-1	0	1	mV
t _{RESP}	Response Time				2	ms

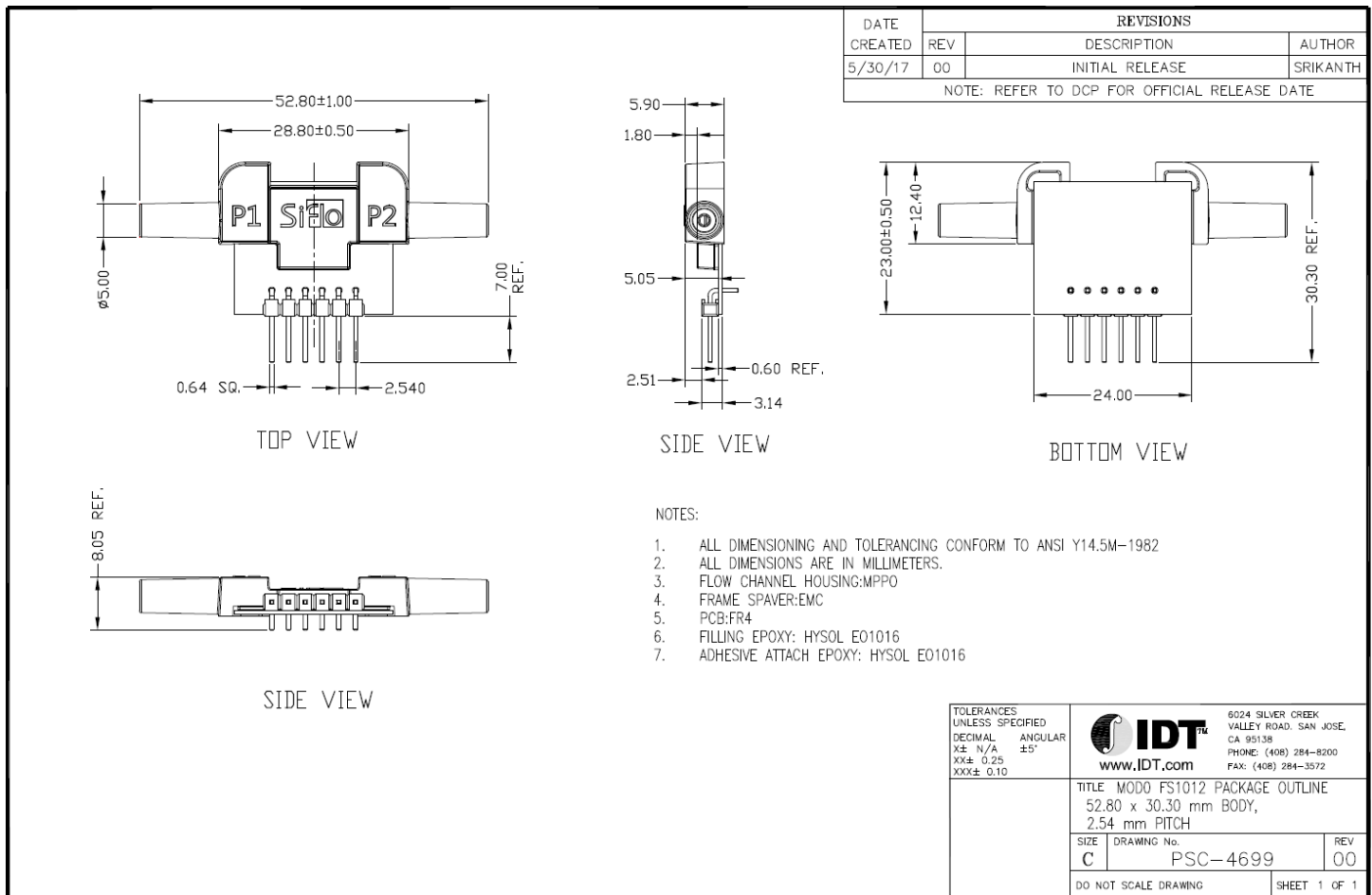
Symbol	Parameter	Conditions	Minimum	Typical	Maximum	Units
Standard Gas Flow Range^{[b], [c]}						
	Gas Flow	FS1012-1020-NG	0		2 (2000)	SLPM (SCCM)
		FS1012-1100-NG	0		10 (10000)	SLPM (SCCM)
Standard Liquid Flow Range^{[b], [c]}						
	Liquid Flow	FS1012-1001-LQ	0		0.5 (500)	SLPM (SCCM)
		FS1012-1002-LQ	0		1.0 (1000)	SLPM (SCCM)

[a] Sensor specifications are tested at the wafer die level.

[b] SLPM: Standard liter per minute.

[c] SCCM: Standard cubic centimeter per minute.

Mechanical Drawings

Figure 4. FS1012 Module Dimensions


Ordering Information

Note: The part code depends on the application. In the part code, NG refers to “non-corrosive gas” and LQ refers to “liquid.”

Orderable Part Number	Description and Package	Shipping Packaging	Temperature
FS1012-1020-NG	0 to 2 SLPM gas flow sensor mounted on a circuit board with a flow housing	Box	0°C to +85°C
FS1012-1100-NG	0 to 10 SLPM gas flow sensor mounted on a circuit board with a flow housing	Box	0°C to +85°C
FS1012-1001-LQ	0 to 0.5 SLPM (500 SCCM) liquid flow sensor mounted on a circuit board with a flow housing	Box	0°C to +85°C
FS1012-1002-LQ	0 to 1.0 SLPM (1000 SCCM) liquid flow sensor mounted on a circuit board with a flow housing	Box	0°C to +85°C

Revision History

Revision Date	Description of Change
July 20, 2017	Initial release of the datasheet.



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